

SL-SMT 3.50/05/180RF 1.5SN BK BX**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Product image

High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**

General ordering data

Version	PCB plug-in connector, male header, Clip-on flange, THT/THR solder connection, 3.50 mm, Number of poles: 5, 180°, Solder pin length (l): 1.5 mm, tinned, black, Box
Order No.	1291320000
Type	SL-SMT 3.50/05/180RF 1.5SN BK BX
GTIN (EAN)	4050118085358
Qty.	50 pc(s).
Product data	IEC: 320 V / 15 A UL: 300 V / 10 A
Packaging	Box

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Technical data

Dimensions and weights

Depth	7.4 mm	Depth (inches)	0.291 inch
Height	12.6 mm	Height (inches)	0.496 inch
Height of lowest version	11.1 mm	Width	24.35 mm
Width (inches)	0.959 inch	Net weight	1.698 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 "	Outgoing elbow	180°
Number of poles	5	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0.03 mm
Solder eyelet hole diameter (D)	1.4 mm	Solder eyelet hole diameter tolerance (D)+	0, 1 mm
Outside diameter of solder pad	2.3 mm	Template aperture diameter	2.1 mm
L1 in mm	14 mm	L1 in inches	0.551 "
Number of rows	1	Pin series quantity	1
Touch-safe protection acc. to DIN VDE 57 106	finger-safe plugged/ back-of-hand-safe unplugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	6 N	Pulling force/pole, max.	6 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIla
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface	tinned	Layer structure of solder connection	2...3 μm Ni
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	100 °C
Temperature range, installation, min.	-30 °C	Temperature range, installation, max.	100 °C

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	12 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV		

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A

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Technical data

Rated data acc. to UL 1059

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 300 V

Rated voltage (Use group D / UL 1059) 300 V

Rated current (Use group B / UL 1059) 10 A

Rated current (Use group D / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Packing

Packaging

Box

VPE length

85 mm

VPE width

85 mm

VPE height

35 mm

Classifications

ETIM 6.0

EC002637

ETIM 7.0

EC002637

ETIM 8.0

EC002637

ETIM 9.0

EC002637

ECLASS 9.0

27-44-04-02

ECLASS 9.1

27-44-04-02

ECLASS 10.0

27-44-04-02

ECLASS 11.0

27-46-02-01

ECLASS 12.0

27-46-02-01

ECLASS 13.0

27-46-02-01

Environmental Product Compliance

REACH SVHC

/

Important note

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Gold-plated contact surfaces on request
- Rated current related to rated cross-section & min. No. of poles.
- Diameter of solder eyelet $D = 1.4 + 0.1 \text{ mm}$
- Solder eyelet diameter $D = 1.5 + 0.1 \text{ mm}$, from 9 poles
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load
- Long term storage of the product with average temperature of 50°C and maximum humidity 70%, 36 months

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www.weidmueller.com**Technical data****Approvals**

Approvals



ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL BASE STATION EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper

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Drawings

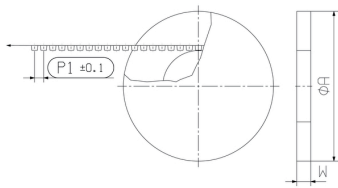
Product image



Dimensional drawing



Dimensional drawing



Dimensional drawing

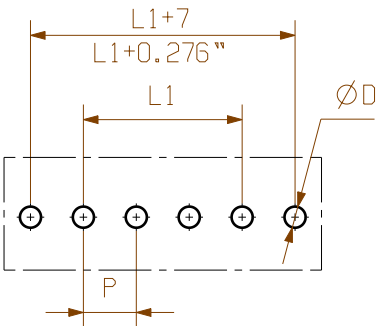


Example of use

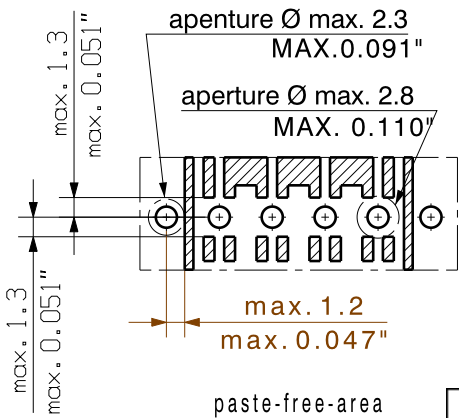


Example of use





hole pattern



paste-free-area

pin length l	tolerance
1,5	0,0 -0,3
2,6	0,0 -0,3
3,2	0,0 -0,3
4,5	0,0 -0,3

24	80,50	3,169	+/- 0.2
23	77,00	3,031	
22	73,50	2,894	
21	70,00	2,756	
20	66,50	2,618	
19	63,00	2,480	+/- 0.15
18	59,50	2,343	
17	56,00	2,205	
16	52,50	2,067	
15	49,00	1,929	
14	45,50	1,791	+/- 0.1
13	42,00	1,654	
12	38,50	1,516	
11	35,00	1,378	
10	31,50	1,240	
9	28,00	1,102	+/- 0.1
8	24,50	0,965	
7	21,00	0,827	
6	17,50	0,689	
5	14,00	0,551	
4	10,50	0,413	+/- 0.1
3	7,00	0,276	
2	3,50	0,138	
n	L1 [mm]	L1 [Inch]	tolerance

shown: SL-SMT 3.50/04/180RF

For the mounting of PCBs, it should be noted that the rated data given in the catalogue relates only to the connection elements. The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller connectors are tested to the DIN VDE 0627 standard, and are valid for its field of application. Provided that the connectors are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

GENERAL TOLERANCE:
DIN ISO 2768-mK

99546/5
08.12.17 HELIS_MA
00

Modification

Date
28.11.2007

Name
HELIS_MA

Drawn

Responsible

Checked

Approved

AMANN_A

HERTEL_S

LANG_T

Scale: 2:1

Supersedes: .

Cat.no.: .

3 34146 11

Drawing no. 3 34146
Sheet 05 of 05 sheets

Issue no.

Issue no.

SL-SMT 3.50/.../180...

STIFTLEISTE
MALE HEADER

Product file: SL-SMT 3.50

7312

Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.